

L Number	Hits	Search Text	DB	Time stamp
1	6222	(adhesive with remov\$5 with (base or carrier or wafer or semiconductor or substrate))	USPAT	2002/09/24 15:14
2	6357	((adhesive or tacky) with remov\$5 with (base or carrier or wafer or semiconductor or substrate))	USPAT	2002/09/24 15:18
3	226	(wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1)	USPAT	2002/09/24 15:42
5	1471117	(base or carrier or wafer or semiconductor or substrate)	USPAT	2002/09/24 15:20
6	1202	(base or carrier or wafer or semiconductor or substrate) with (resist\$3 with deform\$6)	USPAT	2002/09/24 15:20
8	517545	(wafer or semiconductor or substrate)	USPAT	2002/09/24 15:20
7	1	((wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1)) and (resist\$3 with deform\$6)	USPAT	2002/09/24 15:45
9	1	((wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1)) and (resist\$3 with deform\$6)) and adhesive	USPAT	2002/09/24 15:27
10	933	"JEDEC"	USPAT	2002/09/24 15:26
13	3	("JEDEC" and (reusable or (re adj usable))) and adhesive	USPAT	2002/09/24 15:27
15	7	"JEDEC" and (reusable or (re adj usable) or "re-usable")	USPAT	2002/09/24 15:28
14	4	((wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1)) and (reusable or (re adj usable) or "re-usable")	USPAT	2002/09/24 15:32
16	1036	((adhesive\$ or tacky) with (radiation or ultraviolet or radiation or "UV" or thermal) with treat\$4)	USPAT	2002/09/24 15:40
18	163	((adhesive\$ or tacky) with (radiation or ultraviolet or radiation or "UV" or thermal) with treat\$4)) and ((cross adj link\$3) or "cross-linking" or "cross-kinkable")	USPAT	2002/09/24 15:38
19	8347	peel\$1 with strength\$1	USPAT	2002/09/24 15:37
20	104	((adhesive\$ or tacky) with (radiation or ultraviolet or radiation or "UV" or thermal) with treat\$4)) and (peel\$1 with strength\$1)	USPAT	2002/09/24 15:37
22	53	(peel\$1 with strength\$1) with ((cross adj link\$3) or "cross-linking" or "cross-kinkable")	USPAT	2002/09/24 15:58
21	17	((adhesive\$ or tacky) with (radiation or ultraviolet or radiation or "UV" or thermal) with treat\$4)) and (peel\$1 with strength\$1) and ((cross adj link\$3) or "cross-linking" or "cross-kinkable")	USPAT	2002/09/24 15:39
23	2	((adhesive\$ or tacky) with (radiation or ultraviolet or radiation or "UV" or thermal) with treat\$4)) and ((peel\$1 with strength\$1) with ((cross adj link\$3) or "cross-linking" or "cross-kinkable"))	USPAT	2002/09/24 15:40
24	13	(wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1) same (adhesive\$1 or tacky)	USPAT	2002/09/24 15:44
25	23	(base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1) same (adhesive\$1 or tacky)	USPAT	2002/09/24 15:50
27	2	((wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1)) and (resist\$3 with (deform\$6 or warp\$3 or bend\$5 or twist\$3))	USPAT	2002/09/24 15:47
28	3	((base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1) same (adhesive\$1 or tacky)) and (resist\$3 with (deform\$6 or warp\$3 or bend\$5 or twist\$3))	USPAT	2002/09/24 16:05

29	23	(waffle or "JEDEC" or tray or base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1) same (adhesive\$1 or tacky)	USPAT	2002/09/24 15:59
30	3	((waffle or "JEDEC" or tray or base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1) same (adhesive\$1 or tacky)) and (resist\$3 with (deform\$6 or warp\$3 or bend\$5 or twist\$3))	USPAT	2002/09/24 15:53
31	3	((waffle or "JEDEC" or tray or base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1) same (adhesive\$1 or tacky)) and ((resist\$3 or prevent\$3 or avoid\$3) with (deform\$6 or warp\$3 or bend\$5 or twist\$3))	USPAT	2002/09/24 15:53
32	293	(waffle or "JEDEC" or tray or base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1)	USPAT	2002/09/24 15:56
35	43	((peel\$1 with strength\$1) with ((cross adj link\$3) or "cross-linking" or "cross-kinkable")) same (adhesive\$1 or tacky)	USPAT	2002/09/24 15:58
36	34	((peel\$1 with strength\$1) with ((cross adj link\$3) or "cross-linking" or "cross-kinkable")) same (adhesive\$1 or tacky)) and (waffle or "JEDEC" or tray or base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1)	USPAT	2002/09/24 16:00
37	7	((waffle or "JEDEC" or tray or base or carrier or wafer\$1 or semiconductor\$1 or substrate\$1) with transparent with (electromagnetic adj radiation\$1)) and (resist\$3 with (deform\$6 or warp\$3 or bend\$5 or twist\$3))	USPAT	2002/09/24 16:05